

Example list of results corresponding to a single layer film

Film kind	ITO	αFTO	Cr	AI	Ni	Au	Cu	Ag	Ti	Мо	IZO	MAM	FTO
								(APC)					
Film thickness	20~	50~	10~	100~	100~	100~	100~	100	100	100	300	100	40~
unit nm	450	200	300	1000	500	500	2000				10 <	~500	800
Minimum pitch	6	6	6	10	10	20	20	20	20	20	20	20	2
unit µm													(mm)
Minimamu L/S	3/3	3/3	3/3	5/5	5/5	10/10	10/30	10/10	10/10	10/10	10/10	10/10	2/2
unit µm													(mm)
Forming accuracy	±1μ	±1μ	±1μ	$\pm 3 \mu$	$\pm 3 \mu$	±3μ	±5μ	±5μ	±3μ	±3μ	±3μ	±3μ	$\pm 300 \mu$
(Credition use)													
Processing size	400 × 500	300X400	300 × 400	300 × 400	300 × 400	150×150	300 × 400	150×150	300 × 400	300 × 400	300 × 400	300×400	150X150
(Max work)	*300X400												
unit mm													

Minimum pitch · L / S · Processing accuracy also depends on film thickness etc specifications.

We will help you create empty cells etc with thin glass laminating technology cultivated with glass / glass touch panel.

①Processing contents

- Glass + glass laminate (Can step cut)
- Glass + film lamination
 (Specification consultation necessary)

②Processing size

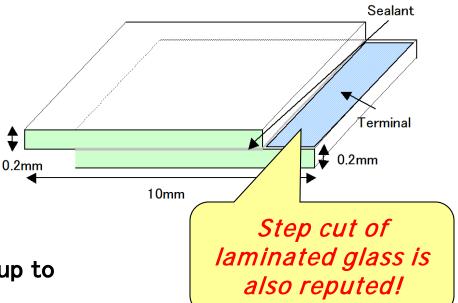
•MAX It is possible to process glass substrates up to 400 mm \times 360 mm.

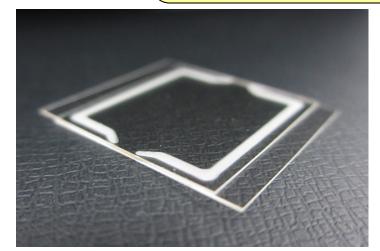
Thinness up / down 0.2mm ~Available

G+F:(Specification consultation necessary)

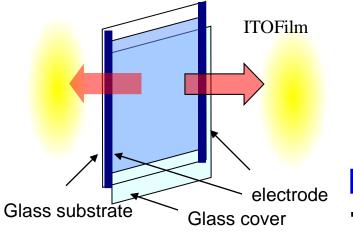
3 Machining record

- Gap between glass and glass : $10 \sim 30 \,\mu$ m
- (Bonding with sealing material)





ITO heater processing





[Application]



- For dew condensation prevention of surveillance cameras and equipment requiring visibility
- Micro flow path etc Want to warm while observing Chemical analysis, for cell culture experiment!
- For aircraft and special vehicle monitors that require full LCD performance!
- To prevent fogging of the mirror in the bathroom and the washroom!

(Size)

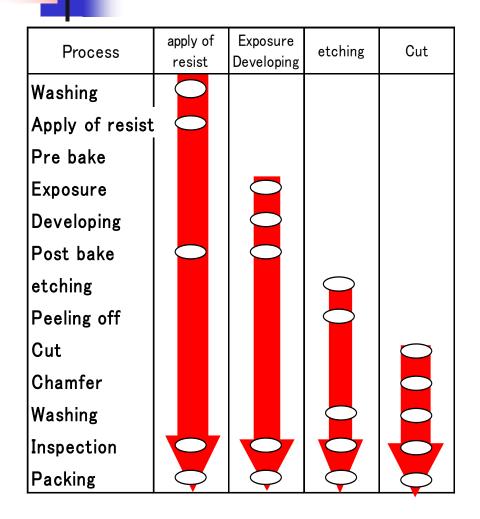
- Minimum 10 mm × 10 mm to maximum 370 mm X 470 mm (panel shape)
- -Minimum to maximum 300 φ (wafer shape)

Assisting various materials evaluation

- I would like you only to apply our own resist.
- Is there any place you can ask for exposure and development only?
- I would like to peel film from substrate!
- · I want to work in a clean room.
- · I want to get a small glass as cheap as possible !

Techno print also responds to such troubles !

Evaluation support for development of various materials







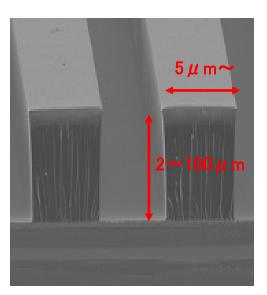




Microstructure formation

Have you been struggling to create high precision jigs for tracking ability evaluation of adhesion / reinforcing agent materials etc. on uneven

substrates?



At TCN, we provide customized types ofµm precision with various resist agents. Pattern shape can be straight / circular (cylindrical) Aspect ratio 5:1 (film thickness 50µm or more) possible, (3:1 actual results)

Application example

· Follow ability evaluation of adhesive, adhesive film, filler (semiconductor PKG etc.)

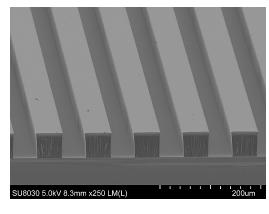
- · Micro folder such as micro LED
- · Cover glass spacer of solar cell etc.

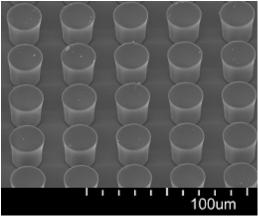
In addition to simulation, evaluation and verification that is close to the actual machine is possible.

By creating a mask, it is possible to divide multiple shapes by changing the line width such as L shape, straight line, circular shape (cylindrical) etc. on the same board. Aspect ratio 5: 1 (film thickness 50 μ m or more) possible,

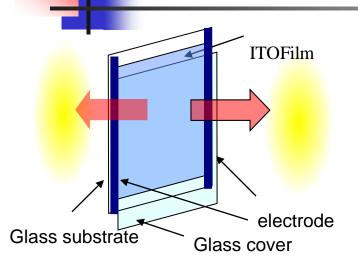
height 2 to 100 μ possible

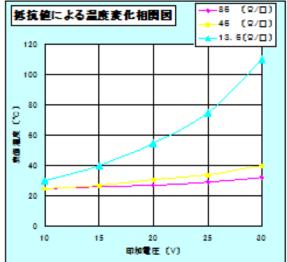
* However, the same height is on the same board.
Substrate size is easy to use up to 300 mm in large format □ 50, 100, 200 mm and any size can be cut.
Glass / silicon wafers etc are possible as base material.





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* A wide FPC can also be crimped to 300 mm ACF! [Size]

- Minimum 10 mm × 10 mm to maximum 370 mm X
 470 mm (panel shape)
- -Minimum to maximum 300 φ (wafer shape)



Light-sensitive resin patterning

①The processing possible film kind

•Register, polyimide, resin black and exposure to light Ag (MAX170 \Box) etc.

Processing size •MAX: 300mm × 300mm *Effective area: \$\phi\$ 300mm

③Processing results

	Line	Space		
Resiser	3 μ m	3 μ m		
Polyimide	10 μ m	10 μ m		
Resin black	7μm	15 μ m		
Photosensitive Ag	10 μ m	10 μ m		